LUCRĂRI PUBLICATE

a.) Lucrări relevante incluse in format electronic în dosar

1. **A. Fodor**, R. Jano, D. Pitica, “Component Placement Optimizations on PCBs for Improved Thermal Behaviour”, Electronics Technology (ISSE), Proceedings of the 2015 38th International Spring Seminar on, in press
2. **Fodor, A.**; Jano, R., "Thermal modelling of IC packages," Design and Technology in Electronic Packaging (SIITME), 2013 IEEE 19th International Symposium for, vol., no., pp.149,152, 24-27 Oct. 2013
3. **Alexandra, F.**; Rajmond, J.; Dan, P., "Flow simulations for component spacing optimization on PCB boards," Design and Technology in Electronic Packaging (SIITME), 2014 IEEE 20th International Symposium for, vol., no., pp.149,152, 23-26 Oct. 2014
4. **A. Fodor**, R. Jano, “Thermal Influences on Electronic Components from the Manufacturing Stage to System Integration”, Acta Tehnica Napocensis Electronics and Telecommunications, vol 56 (1/2015), pp. 17-20 2015.
5. **A. Fodor**, G. Chindris, D. Pitica and R. Jánó, "Guidelines on thermal management solutions for modern packaging technologies - a review," Design and Technology in Electronic Packaging (SIITME), 2015 IEEE 21st International Symposium for, Brasov, 2015, pp. 41-44.
6. **A. Fodor**, G. Chindris, D. Pitica, "Enhancing Thermal Capabilities of Component Packaging" Design and Technology in Electronic Packaging (SIITME), 2016 IEEE 22nd International Symposium for, Oradea
7. **A. Fodor**, G. Chindris, D. Pitica and R. Jano, “Task allocation for thermal optimization in multicore systems,” *2016 IEEE 12th International Conference on Intelligent Computer Communication and Processing (ICCP)*, Cluj-Napoca, 2016, pp. 349-352.
8. **A. Fodor**, R. Jano and D. Pitica, "Investigations of thermal influences on clock speed of embedded devices," *2017 40th International Spring Seminar on Electronics Technology (ISSE)*, Sofia, Bulgaria, 2017, pp. 1-4.
9. **A. Fodor**, R. Jánó, G. Chindris and D. Pitica, "Thermal via placement for high-power applications," 2017 IEEE 23rd International Symposium for Design and Technology in Electronic Packaging (SIITME), Constanta, 2017, pp. 223-226. doi: 10.1109/SIITME.2017.8259895

b.) Teza de docorat

Thermal management solutions for modern embedded technologies – Soluții pentru managementul termic în tehnologii embedded moderne, Universitatea Tehnică din Cluj-Napoca, 27 Ianuarie 2017.

c.) Publicații în extenso, apărute în lucrări ale principalelor conferințe internaționale de specialitate

1. C. Fărcaş, **A. Fodor**, D. Pitică, "Thermal Analysis of Heat Sinks for a Power Thyristor Module", Advanced Materials Research, Vol. 1114, pp. 38-43, Jul. 2015
2. Rajmond, J.; **Fodor, A.**, "Thermal management of embedded devices" Electronics Technology (ISSE), 2013 36th International Spring Seminar on, pp.30-34, 8-12 May 2013
3. Jano, R.; **Fodor, A.**, "Soldering profile optimization for through-hole and surface mounted ceramic capacitors," Electronics Technology (ISSE), Proceedings of the 2014 37th International Spring Seminar on, pp.170-175, 7-11 May 2014
4. **Fodor, A.**; Jano, R.; Pitica, D., "Thermal influences on IC packages during manual soldering process", Electronics Technology (ISSE), Proceedings of the 2014 37th International Spring Seminar on, vol., no., pp.54,57, 7-11 May 2014
5. Jano, R.; **Fodor, A.**, "Educational Tool for Capacitor Lifetime Prediction", Electronics Technology (ISSE), Proceedings of the 2015 38th International Spring Seminar on, in press
6. **A. Fodor**, R. Jano, D. Pitica, "Component Placement Optimizations on PCBs for Improved Thermal Behaviour", Electronics Technology (ISSE), Proceedings of the 2015 38th International Spring Seminar on, in press
7. **Fodor, A.**; Jano, R., "Thermal modelling of IC packages," Design and Technology in Electronic Packaging (SIITME), 2013 IEEE 19th International Symposium for, vol., no., pp.149,152, 24-27 Oct. 2013
8. **Alexandra, F.**; Rajmond, J.; Dan, P., "Flow simulations for component spacing optimization on PCB boards," Design and Technology in Electronic Packaging (SIITME), 2014 IEEE 20th International Symposium for, vol., no., pp.149,152, 23-26 Oct. 2014
9. **A. Fodor**, R. Jano, "Thermal Influences on Electronic Components from the Manufacturing Stage to System Integration", Acta Tehnica Napocensis Electronics and Telecommunications, vol 56 (1/2015), pp. 17-20 2015.
10. Baciu, I.H.; Viman, L.; **Fodor, A.**; Chindris, G., "Advanced methods of generating signals to command switching converters," Electronics Technology (ISSE), 2013 36th International Spring Seminar on, vol., no., pp.202,205, 8-12 May 2013'
11. **A. Fodor**, G. Chindris, D. Pitica and R. Jánó, "Guidelines on thermal management solutions for modern packaging technologies - a review," Design and Technology in Electronic Packaging (SIITME), 2015 IEEE 21st International Symposium for, Brasov, 2015, pp. 41-44.
12. **A. Fodor**, G. Chindris, D. Pitica, "Enhancing Thermal Capabilities of Component Packaging" Design and Technology in Electronic Packaging (SIITME), 2016 IEEE 22nd International Symposium for, Oradea
13. **A. Fodor**, G. Chindris, D. Pitica and R. Jano, "Task allocation for thermal optimization in multicore systems," *2016 IEEE 12th International Conference on Intelligent Computer Communication and Processing (ICCP)*, Cluj-Napoca, 2016, pp. 349-352.
14. R. Jánó, **A. Fodor** and A. I. Ilieş, "Simulation and educational tool for fault modelling in logic circuits," *2016 39th International Spring Seminar on Electronics Technology (ISSE)*, Pilsen, 2016, pp. 476-479.
    doi: 10.1109/ISSE.2016.7563244

15. H. Baciu, A. Taut, G. Chindris and **A. Fodor**, “Mathematical model for a quasi-resonant converter,” *2015 IEEE 21st International Symposium for Design and Technology in Electronic Packaging (SIITME)*, Brasov, 2015, pp. 213-216.
16. **A. Fodor**, R. Jano and D. Pitica, "Investigations of thermal influences on clock speed of embedded devices," *2017 40th International Spring Seminar on Electronics Technology (ISSE)*, Sofia, Bulgaria, 2017, pp. 1-4.
17. M. A. Tăut, G. Chindriş, D. Pitică and **A. Fodor**, "Model-in-the-Loop for determining the parameters of a DC motor," 2017 IEEE 23rd International Symposium for Design and Technology in Electronic Packaging (SIITME), Constanta, 2017, pp. 267-273. doi: 10.1109/SIITME.2017.8259906
18. R. Jánó, **A. Fodor** and A. I. Ilieş, "Compact SD card backup system for use in photography," 2017 IEEE 23rd International Symposium for Design and Technology in Electronic Packaging (SIITME), Constanta, 2017, pp. 145-148. doi: 10.1109/SIITME.2017.8259878
19. **A. Fodor**, R. Jánó, G. Chindris and D. Pitica, "Thermal via placement for high-power applications," 2017 IEEE 23rd International Symposium for Design and Technology in Electronic Packaging (SIITME), Constanta, 2017, pp. 223-226. doi: 10.1109/SIITME.2017.8259895